DECLARATION AND POWER OF AITORNEY

	ntor, I hereby declare that:	
My residence, post offi	ce and citizenship are as stated below next to my name,	
names are listed bel	nal, first and sole inventor (if only one name is listed below) or ow) of the subject matter claimed and for which a pay SYSTEM AND METHOD ON A FORWAR	ent to amount on the insection and that
	[] was filed on as Application Serial amended on (if applicable	No. and was
I hereby state that I h amended by any amen	ave reviewed and understand the contents of the above identificant referred to above.	fied specification, including the claims, as
Secondary Code of Federal Regul		
America, listed below Cartificate, or of any Po	priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any fif any PCT international application which designated at least and have also identified below, by checking the box, any fCT international application having a filing date before that of the	present application for patent or inventor's
Prior Foreign Applies Number	country	Foreign Filing Date Month/Dav/Year
P2000-73665	KOREA	December 06, 2000
I hereby claim the bane	fit under 35 U.S.C.119(e) of any United States provisional appli	cation(s) listed below.
8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8	fit under 35 U.S.C.119(e) of any United States provisional appli Filing Date(Month/Day/Year)	cation(s) listed below.
I hereby claim the bene Application Number(s) I hereby claim the bene designating the United not disclosed in the pri 112, I acknowledge th		365(c) of any PCT international application of each of the claims of this application is avoided by the first paragraph of 35 U.S. C. as defined in 37 CFR 1.56 which became
I hereby claim the bene Application Number(s) I hereby claim the bene designating the United not disclosed in the pri 112, I acknowledge th	fit under 35, U. S. C. 120 of any United States application(s), or States of America, listed below and, intofar as the subject matter or United States or PCT international application in the manner jeduty to disclose information which is material to patentability ling date of the prior application and the national or PCT international contents.	365(c) of any PCT international application of each of the claims of this application is avoided by the first paragraph of 35 U.S. C. as defined in 37 CFR 1.56 which became



I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vasquez, Registration No. 38,647; Stuart I. Smith, Registration No. 42,159; Carol L. Druzbick, Registration No. 40,287; Anthony H.Nourse, Registration No. 46,121; and Margaret A. Burke, Registration No. 34,474, all of

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		Chantilly, Virgini			
with full power of sub Office connected there	stitution and revocation, with, and all future corre	to prosecute this applicati	on and to transact all bu	siness in the Pater	nt and Trademark
************	*************	**************	***********	***************	**********
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